



219.40240X00

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Takashi KUMAMOTO

Serial No.: 09/893,588

Filed: 29 June 2001

For: MULTI-PURPOSE PLANARIZING/BACK-GRIND/PRE-UNDERFILLED
ARRANGEMENTS FOR BUMPED WAFERS AND DIE

Art Unit: 2827

Examiner: Alonzo CHAMBLISS

RECEIVED
APR 10 2003
TECHNOLOGY CENTER 2800

AMENDMENT

Assistant Commissioner
for Patents
Washington, D.C. 20231

09 April 2003

Sir:

In response to the Office Action having a USPTO mailing date of
09 January 2003, the following is respectfully submitted in connection with the above-
identified application.

CLEAN COPY OF AMENDED PORTIONS OF THE APPLICATION

In order to comply with USPTO requirements, the following represents a clean
copy of portions of the application as amended via the attached "Appendix - Version
With Markings To Show Changes Made".